

**DEVICE ENGINEERING  
INCORPORATED**

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# DEI1026A

## Six Channel Discrete-to-Digital Interface Sensing Open/Ground Signals

### Features

- Senses six Open/Ground Inputs
- Inputs are lightning protected to DO-160G Level 3
- ABD0100 compliant input voltage threshold
- TTL/CMOS-Compatible Tri-State Outputs
- Package / Temperature Options:
  - 16 lead .150" SOIC, -55 °C /+85 °C or 125 °C
  - 16 lead Ceramic 300 mil SOP, -55 °C /+125 °C



SOIC package option

### Functional Description

The DEI1026A is a six channel discrete-to-digital interface BiCMOS device. It senses six Open/Ground discrete signals of the type commonly found in avionic systems. The inverted 3-state outputs are TTL/CMOS compatible and are enabled by the  $\overline{OE}$  and  $\overline{CE}$  pins. The inputs are lightning protected to meet the requirements of DO160D Sec 22 Waveforms 3, 4, and 5, Level 3. See figures 5-7. The device is available in a 16 lead .150" SOIC and .300" Ceramic SOP.

With its reliability, low cost, operating range, and lightning protection, the DEI1026A meets a large variety of interface requirements for aerospace applications.

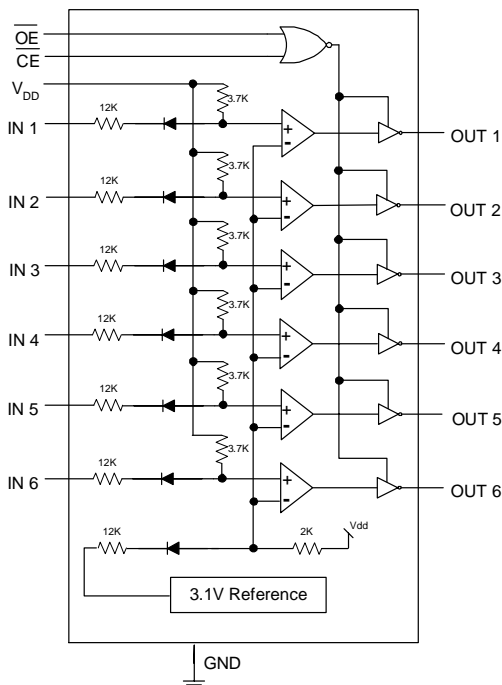


Figure 1: Concept Drawing

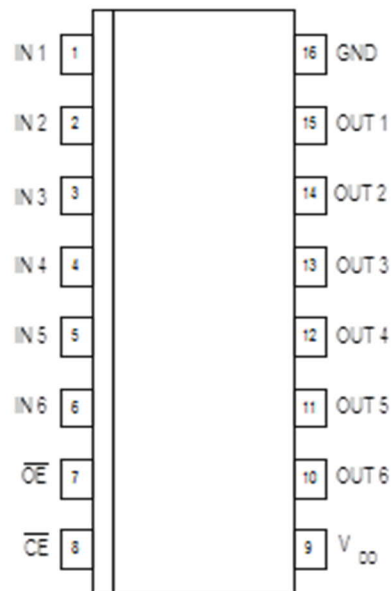


Figure 2: Pinout Diagram

## Electrical Characteristics

**Table 1: Absolute Maximum Ratings**

PARAMETER	MIN	MAX	UNITS	
Supply Voltage $V_{DD}$	-0.3	7.0	V	
Discrete Input Voltage (Pins 1-6)	-5	+40 *	V	
Digital Input Voltage ( $\overline{CE}$ and $\overline{OE}$ )	$V_{SS} - 0.3$	$V_{DD} + 0.3$	V	
Lightning Protection (Pins 1-6) DO160G, Waveform 3; Level 3 pin injection DO160G, Waveforms 4, and 5; Level 3 pin injection	-660 -330	+660 +330	V	
Junction Temperature		145	°C	
Storage Temperature	Plastic Ceramic	-65 -55	150 150	°C
Operating Free Air Temperature	Plastic Ceramic	-55 -55	85 125	°C
Peak Body Temperature	Plastic, G Package Ceramic		260 240	°C

The DE11026A contains circuitry to protect inputs from damage due to electrostatic discharge. It has been characterized per JESD22-A114 Human Body Model to Class 1C. Observe precautions for handling and storing Electrostatic Sensitive Devices.

\* The DE11026A will withstand the transient surge DC voltage step function loci limits for category B equipment per MIL-STD-704A.

**Table 2: DE11026A Device Operating Characteristics**

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Supply Voltage	$V_{DD}$		4.5	5.0	5.5	V
Free Air Operating Temp.	$T_A$	$V_{DD} = 4.5 - 5.5$ V Plastic Ceramic	-55 -55		85 125	°C
Logic Output Sink Current	$I_{OL}$	$V_{DD} = 4.5 - 5.5$ V			5.0	mA
Logic Output Source Current	$I_{OH}$	$V_{DD} = 4.5 - 5.5$ V	-5.0			mA

**Table 3: DE11026A Logic Truth Table**

$\overline{CE}$ Chip Enable	$\overline{OE}$ Output Enable	$IN_N$ Discrete Input	$OUT_N$ Output
0	0	Open	0
0	0	Ground	1
1	X	X	High Z
X	1	X	High Z

**Table 4A: DEI1026A-SES Electrical Characteristics**  
 (T<sub>A</sub> = -55°C to +85°C , V<sub>DD</sub> = 4.5 to 5.5 V, Unless otherwise noted)

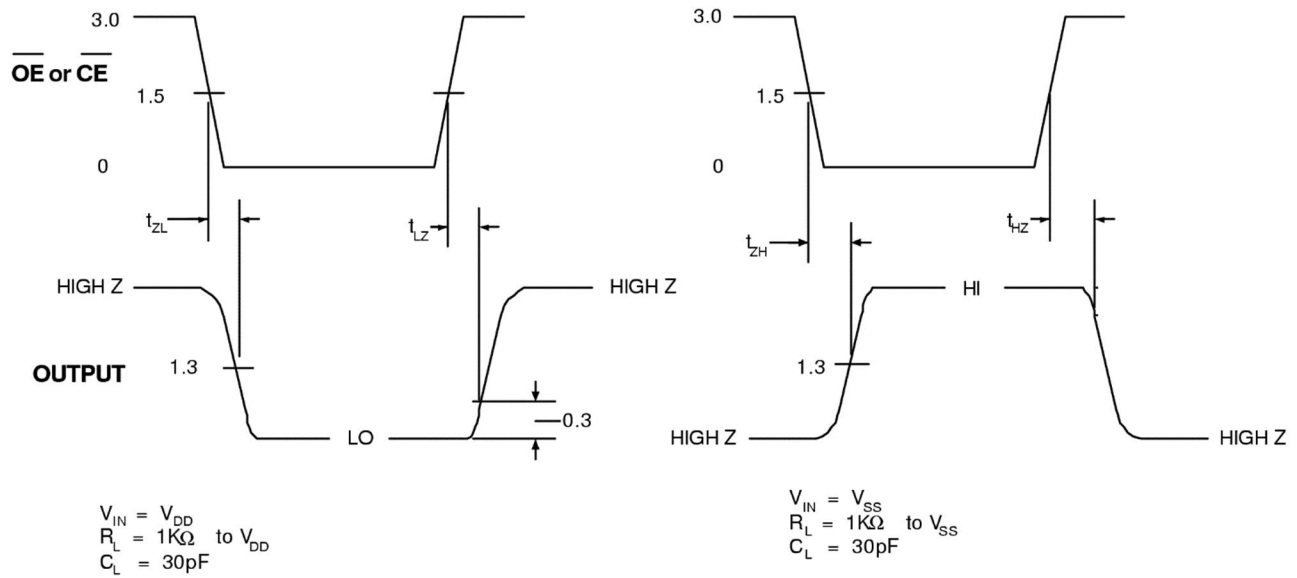
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
<b>Power Supply Characteristics</b>						
Supply Current	I <sub>DD</sub>	V <sub>IN</sub> = V <sub>DD</sub> (all inputs) V <sub>DD</sub> = 5.5 V		5	10	mA
<b>Discrete Input Characteristics</b>						
Ground state input voltage	V <sub>SG</sub>	Voltage source from input terminal to ground for Logic High Output.			3.5	V
Open state input voltage	V <sub>SO</sub>	Voltage source from input terminal to ground for Logic Low Output.	4.1			V
Ground state input resistor	R <sub>IG</sub>	Resistor from input to ground to guarantee Logic High Output.	0		100	Ω
Open state input resistor	R <sub>IO</sub>	Resistor from input to ground to guarantee Logic Low Output.	500k			Ω
Input source current	I <sub>IO</sub>	Current sourced into 100 Ohm resistor to Ground.	-100	-330		μA
Reverse leakage current	I <sub>IR</sub>	V <sub>IN</sub> = 35 V, V <sub>DD</sub> = 0 V			100	μA
<b>Logic Input Characteristics</b>						
$\overline{CE}$ , $\overline{OE}$ input logic 1 level	V <sub>IH</sub>		2.0			V
$\overline{CE}$ , $\overline{OE}$ input logic 0 level	V <sub>IL</sub>				0.8	V
<b>DC Output Characteristics</b>						
Output logic 1 level (TTL)	V <sub>OH</sub>	I <sub>OH</sub> = -5 mA	2.4			V
Output logic 0 level (TTL)	V <sub>OL</sub>	I <sub>OL</sub> = 5 mA (2)			0.4	V
Output logic 1 level (CMOS)	V <sub>OH</sub>	I <sub>OH</sub> = -100 μA	V <sub>DD</sub> - 50mV			V
Output logic 0 level (CMOS)	V <sub>OL</sub>	I <sub>OL</sub> = 100 μA			V <sub>SS</sub> + 50mV	V
Off-state Output Current	I <sub>OZ</sub>	$\overline{OE} = V_{DD}$ V <sub>DD</sub> = 5.5 V V <sub>OUT</sub> = 0 or V <sub>DD</sub>			+/-10	μA
<b>Switching Characteristics [1]</b>						
I/O propagation delay	t <sub>HL</sub> , t <sub>LH</sub>	Refer to Figure 4.			150	ns
Delay from $\overline{CE}$ or $\overline{OE}$ input (with output low) to output HI-Z	t <sub>LZ</sub>	Refer to Figure 3.			25	ns
Delay from $\overline{CE}$ or $\overline{OE}$ input (with output HI-Z) to output low	t <sub>ZL</sub>	Refer to Figure 3.			25	ns
Delay from $\overline{CE}$ or $\overline{OE}$ input (with output high) to output HI-Z	t <sub>HZ</sub>	Refer to Figure 3.			25	ns
Delay from $\overline{CE}$ or $\overline{OE}$ input (with output HI-Z) to output high	t <sub>ZH</sub>	Refer to Figure 3.			25	ns

**Table 4B: DE11026A-xMx Electrical Characteristics**  
 (T<sub>A</sub> = -55°C to +125°C, V<sub>DD</sub> = 4.5 to 5.5 V, Unless otherwise noted)

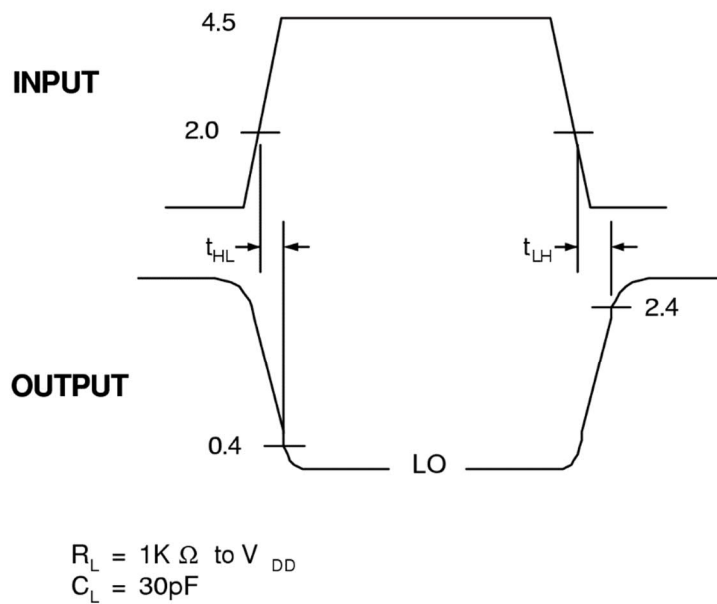
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
<b>Power Supply Characteristics</b>						
Supply Current	I <sub>DD</sub>	V <sub>IN</sub> = V <sub>DD</sub> (all inputs) V <sub>DD</sub> = 5.5 V		5	10	mA
<b>Discrete Input Characteristics</b>						
Ground state input voltage	V <sub>SG</sub>	Voltage source from input terminal to ground for Logic High Output.			3.5	V
Open state input voltage	V <sub>SO</sub>	Voltage source from input terminal to ground for Logic Low Output.	4.1			V
Ground state input resistor	R <sub>IG</sub>	Resistor from input to ground to guarantee Logic High Output.	0		100	Ω
Open state input resistor	R <sub>IO</sub>	Resistor from input to ground to guarantee Logic Low Output.	500k			Ω
Input source current	I <sub>IO</sub>	Current sourced into 100 Ohm resistor to Ground.	-100	-330		μA
Reverse leakage current	I <sub>IR</sub>	V <sub>IN</sub> = 35 V, V <sub>DD</sub> = 0 V			100	μA
<b>Logic Input Characteristics</b>						
$\overline{\text{CE}}$ , $\overline{\text{OE}}$ input logic 1 level	V <sub>IH</sub>		2.0			V
$\overline{\text{CE}}$ , $\overline{\text{OE}}$ input logic 0 level	V <sub>IL</sub>				0.8	V
<b>DC Output Characteristics</b>						
Output logic 1 level (TTL)	V <sub>OH</sub>	I <sub>OH</sub> = -5 mA	2.4			V
Output logic 0 level (TTL)	V <sub>OL</sub>	I <sub>OL</sub> = 5 mA (2)			0.4	V
Output logic 1 level (CMOS)	V <sub>OH</sub>	I <sub>OH</sub> = -100 μA	V <sub>DD</sub> - 50mV			V
Output logic 0 level (CMOS)	V <sub>OL</sub>	I <sub>OL</sub> = 100 μA			V <sub>SS</sub> + 50mV	V
Off-state Output Current	I <sub>OZ</sub>	$\overline{\text{OE}} = V_{DD}$ V <sub>DD</sub> = 5.5 V V <sub>OUT</sub> = 0 or V <sub>DD</sub>			+/-10	μA
<b>Switching Characteristics [1]</b>						
I/O propagation delay	t <sub>HL</sub> , t <sub>LH</sub>	Refer to Figure 4.			170	ns
Delay from $\overline{\text{CE}}$ or $\overline{\text{OE}}$ input (with output low) to output HI-Z	t <sub>LZ</sub>	Refer to Figure 3.			30	ns
Delay from $\overline{\text{CE}}$ or $\overline{\text{OE}}$ input (with output HI-Z) to output low	t <sub>ZL</sub>	Refer to Figure 3.			30	ns
Delay from $\overline{\text{CE}}$ or $\overline{\text{OE}}$ input (with output high) to output HI-Z	t <sub>HZ</sub>	Refer to Figure 3.			30	ns
Delay from $\overline{\text{CE}}$ or $\overline{\text{OE}}$ input (with output HI-Z) to output high	t <sub>ZH</sub>	Refer to Figure 3.			30	ns

**Notes:**

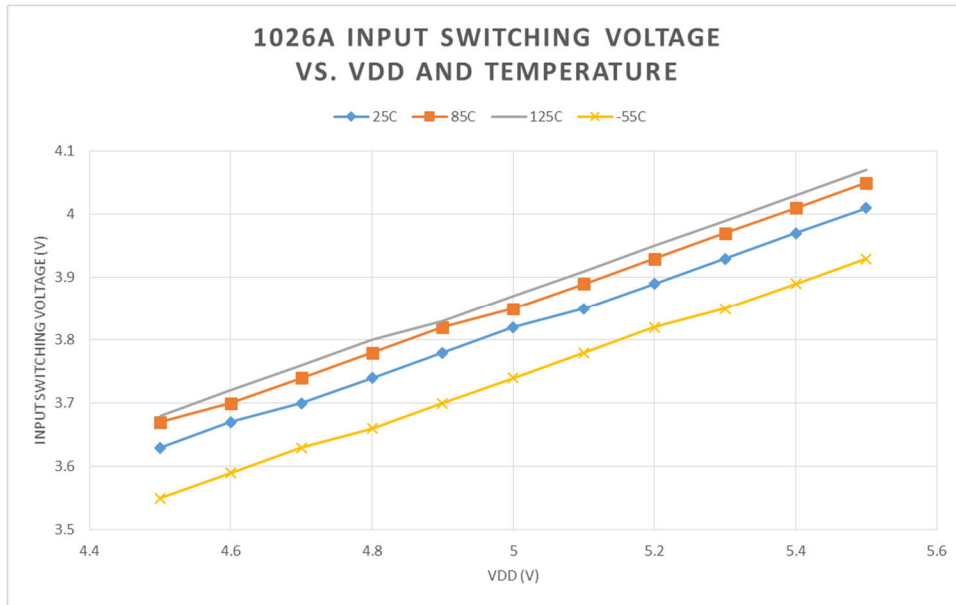
1. Guaranteed by design and not production tested.
2. Limit the sum of all IOL currents to 20 ma. The Vsg spec may exceed limit beyond this current.



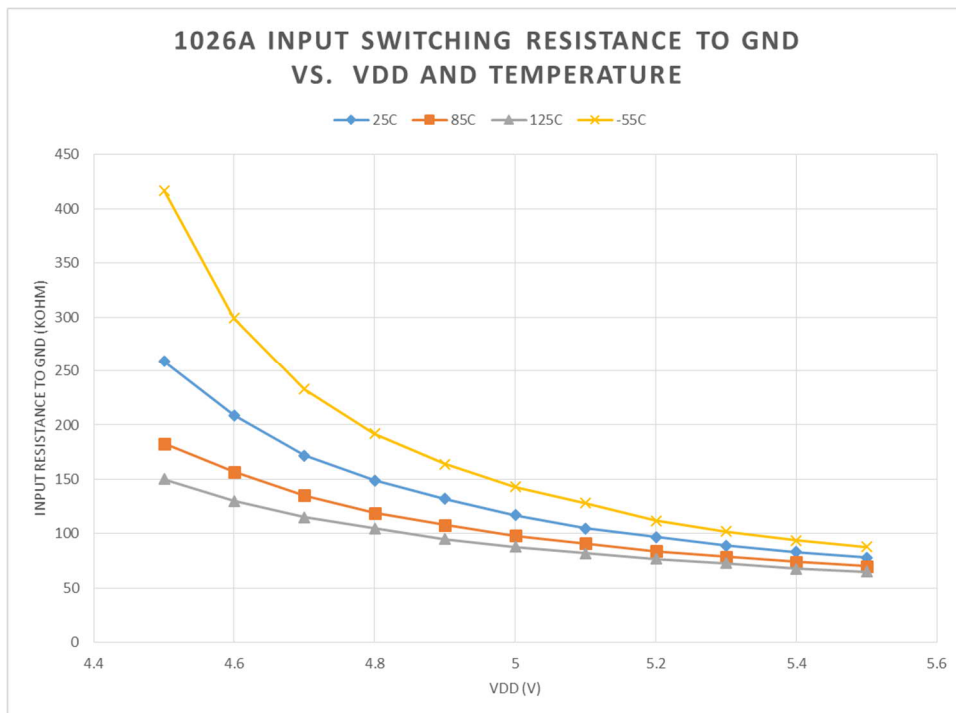
**Figure 3: Enable to Output Propagation Delay**



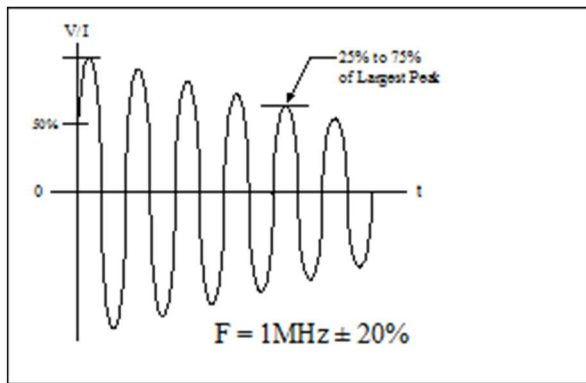
**Figure 4: Input to Output Propagation Delay**



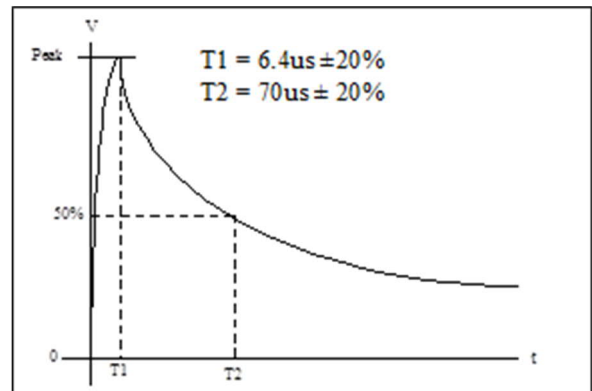
**Figure 5 Input Switching Threshold Voltage Characteristics**



**Figure 6 Input Switching Resistance to Ground Characteristics**



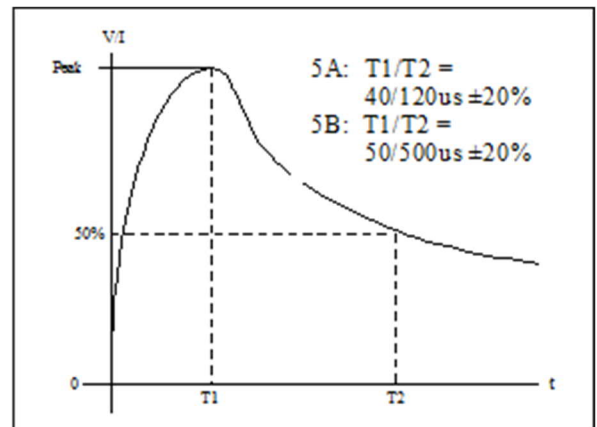
DO160 WF3 Voc/Isc Waveform



DO160 WF4 Voc/Isc Waveform

Notes:

1. DO160G pin injection Level 3 waveforms.
2. Voltage tolerance: +20%, -0%
3. Waveform Source Impedance characteristics:
  - Waveform 3 Voc/Isc = 600 V / 24 A => 25 Ω
  - Waveform 4 Voc/Isc = 300 V / 60 A => 5 Ω
  - Waveform 5A Voc / Isc = 300V / 300A => 1 Ω



DO160 WF5 Voc/Isc Waveform

Figure 7 DO160G Pin Injection Test Waveforms

## Package Characteristics

Table 5: Package Characteristics		
PACKAGE TYPE	16 Lead SOIC Narrow Body, Green	16 Lead Ceramic SOP
REFERENCE	16L SOIC NB G	16L CSOP
<b>THERMAL RESISTANCE:</b>		
$\theta_{JA}$ (4 layer PCB with Power Planes)	~74 °C/W	-
$\theta_{JC}$	~30 °C/W	23 °C/W
JEDEC MOISTURE SENSITIVITY LEVEL (MSL)	MSL 1 / 260°C	Hermetic
LEAD FINISH MATERIAL / JEDEC Pb-free CODE	NiPdAu e4	Au e4
Pb-Free DESIGNATION	RoHS Compliant	Pb Free
JEDEC REFERENCE	MS-012-AC	-

16L SOIC NB G

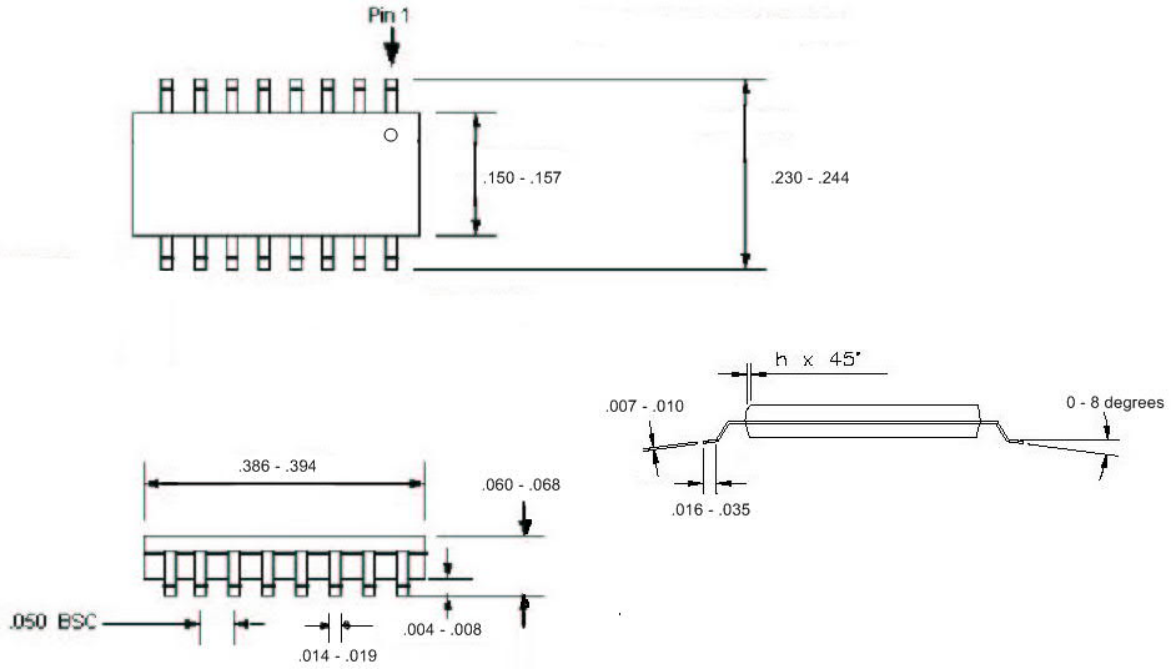


Figure 8: 16L SOIC Mechanical Outline

16L CSOP

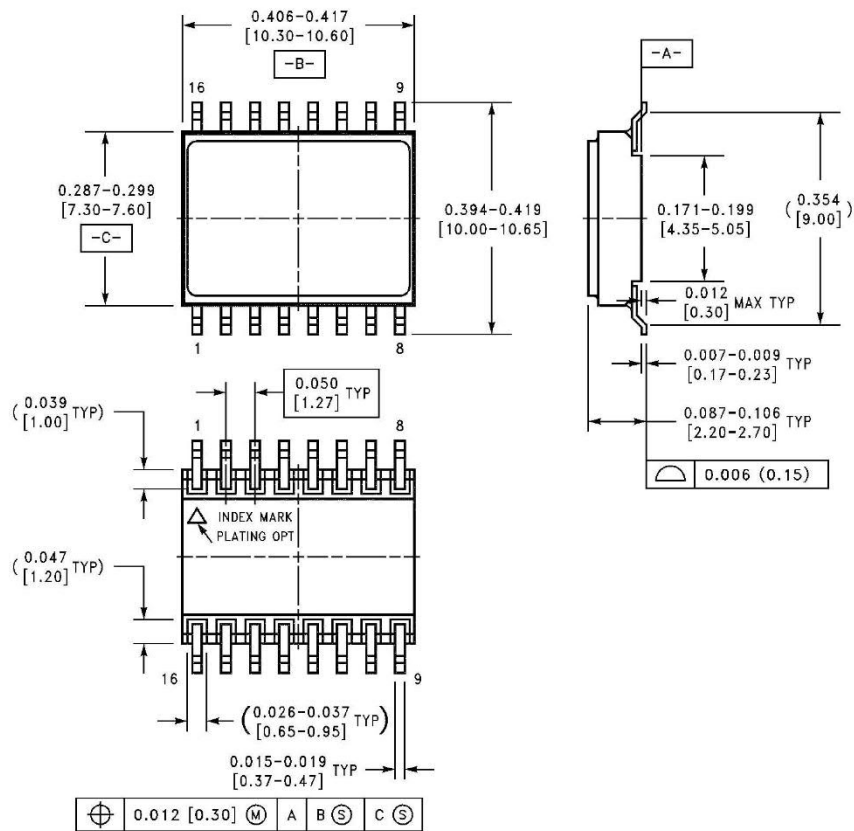


Figure 9: 16L CSOP Mechanical Outline

## Ordering Information

<b>Table 6: Ordering Information</b>				
<b>DEI PART NUMBER</b>	<b>MARKING (1)</b>	<b>PACKAGE</b>	<b>OP. TEMP. RANGE</b>	<b>PROCESSING</b>
DEI1026A-SES-G	DEI1026A-SES E4	16L SOIC NB G	-55 / +85 °C	Standard
DEI1026A-SMS-G	DEI1026A-SMS E4 (3)	16L SOIC NB G	-55 / +125 °C	Standard
DEI1026A-WMS	DEI1026A-WMS	16 lead ceramic SOP	-55 / +125 °C	Standard
DEI1026A-WMB	DEI1026A-WMB	16 lead ceramic SOP	-55 / +125 °C	Burn In, 96 hr @ 125 °C
<b>NOTES:</b> 1. All packages marked with Lot Code and Date Code. 2. "E4" after Date Code Denotes Pb Free category. 3. Alternate marking is –SES + Blue Dot				

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